NO. :



APPROVAL SHEET

MULTILAYER CERAMIC CAPACITOR

Automotive Grade (AEC-Q200 Qualified)

Approved by customer : (signing or stamping here)

| SAM | WHA CAPACITOR CO | D., LTD. |
|-------------|------------------|-------------|
| Prepared by | Checked by | Approved by |
| 2485 | for | 74 |

2020. 01. 10.

SAMWHA CAPACITOR CO., LTD.

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| < | < SPECIFICATION SUMMARY > | | | | | | | | | | | |
|-----------------------|---------------------------|----------------|--|--|--|--|--|--|--|--|--|--|
| SAMWHA Part no. | | CQ2 | 012X7R224K500NRE | | | | | | | | | |
| Туре | 1 | *MLCC fo | or Automotive Application | | | | | | | | | |
| Items | Specification | Unit | Test Conditions | | | | | | | | | |
| Capacitance | 220 | nF | _ Testing Frequency : 1 ±0.1 kHz | | | | | | | | | |
| Capacitance Tolerance | ± 10 | % | Testing Voltage : 1 ±0.2 Vrms | | | | | | | | | |
| Dissipation Factor | Max. 12.5 | % | Should be measured at 25 °C. | | | | | | | | | |
| Insulation Resistance | Min. 227.2 | MΩ | Should be measured with a DC voltage not exceeding rated voltage at 25 °C for 2 minutes of charging. | | | | | | | | | |
| | 2.00 ±0.20 | L (mm) | Capacitance Tolerance Code page 1/9 | | | | | | | | | |
| Chip Size | 1.25 ±0.15 | W (mm) | Chip size page 2/9 | | | | | | | | | |
| | 1.25 ±0.15 | T (mm) | Characteristics & Test Method page 3/9~6/9 | | | | | | | | | |
| | *Thin Lay | ver Large-Ca | apacitance Type | | | | | | | | | |

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| | | | | ST | AND | ARC |) | | | N | 0 | SW | / - Q - 01 | |
|--|-------------------|--------------------|--|---------|------------------|------------------------------|-------------------|-----------------|---------------------|-----------------|-------|----------|------------|--|
| Enactment: Feb. 1, 2010 | | MU | MULTILAYER CERAMIC CAPACITOR Automotive Grade | | | | | | | Pa | age | 1 / 9 | | |
| 1. General Code | | | | | | | | | | | | | | |
| (1) Type Designation | on | | | | | | | | | | | | | |
| <u>C</u> (* | | 2012 (2) | <u>X7F</u> (3) | | 24 (4) | <u>K</u> (5) | <u>500</u> (6) | <u>N</u> (7) | <u>R</u> (8) | <u>E</u> (9) |) | | | |
| 1) Multilayer Cer | | | | | | . , | (0) | (-) | (0) | (0) | , | | | |
| 2) Size Code : | This is | s expre | ssed i | n tens | s of a | millim | | t two | digits | are wi | dth. | | | |
| 3) Temperature (| Coeffici | ent Co | de | | | | | | | | | | | |
| Classificat | on | | Code | | Т | empera | | - | | Capa | | e Tolera | ance | |
| Class | | | COG | | | | o +125 | | | | ±30 p | | | |
| | | X7R | | | -55 to +125℃ | | | | ±1 | | | | | |
| Class | | X7S | | | -55 to +125°C | | | ±22% | | | | | | |
| | | | X7T X6S | | | -55 to +125℃ -55 to +105℃ | | | +22% ~ -33% +22% | | | | | |
| The first two ex) 104 = 100 R denotes 8R2 = 8.2 | 0000 p s decir | ъF | nts sig | Inifica | nt figu | ires ar | nd the | last c | ligit de | enotes | the n | umber | of zero | |
| 5) Capacitance T | oleran | ce Coo | le | | | | | | | | | | | |
| Code | | | Toleran | се | | | | Code | | | Tole | rance | | |
| В | | | ± 0.1 p | oF | | | | G | | | ± 2 | .0 % | | |
| C | | | ± 0.25 | | | | | J | | | | 5 % | | |
| D | | | ± 0.5 p | | | | | K | | | | 0 % | | |
| F 6) Voltage Code | | | ± 1.0 9 | % | | | | M | | | ± 2 | 20 % | | |
| Code 6R3 | 100 | 160 | 250 | 350 | 500 | 101 | 201 | 251 | 501 | 631 | 102 | 202 | 302 | |
| Rated DC | DC | DC | DC | DC | DC | DC | DC | DC | DC | DC | DC | DC | DC | |
| Voltage 6.3V | 10V | 16V | 25V | 35V | 50V | 100V | 200V | 250V | 500V | | 1KV | 2KV | 3KV | |
| 7) Termination C N : Nickel-Tin A : Nickel-Tin | Plate | -> Sc | oft Terr | ninatio | on Tyj | pe | | | | | | | | |
| 8) Packing Code R : 7" Reel T | ype, | L : 1 | 3" Ree | І Туре | e, B | 8 : Bul | k Type | e | | | | | | |

9) Thickness option

| Thickne | ess (mm) | Cada | Thickne | ss (mm) | Code | |
|---------|--------------|-------|---------|--------------|------|--|
| t | Tolerance(±) | Code | t | Tolerance(±) | Code | |
| 0.50 | 0.05 | Blank | 1.35 | 0.20 | Н | |
| 0.60 | 0.10 | A | 1.60 | 0.20 | l | |
| 0.80 | 0.10 | В | 1.80 | 0.20 | J | |
| 0.85 | 0.15 | В | 2.00 | 0.25 | К | |
| 1.00 | 0.15 | E | 2.50 | 0.25 | L | |
| 1.10 | 0.15 | E | 2.80 | 0.30 | М | |
| 1.15 | 0.15 | E | 3.20 | 0.30 | Ν | |
| 1.25 | 0.15 | E | 5.00 | 0.40 | 0 | |
| 1.30 | 0.20 | E | | | | |

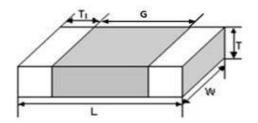
*3216 Size \geq 2.2 μ F 100V \Rightarrow T : Tol±0.30

2. Temperature Characteristics

See Page 6/9 (No.21)

3. Constructions and Dimensions

(1) Dimensions



| | | Dimension | | | | | | | | | |
|-----------|----------|-----------|--------|------|--------|----------|---------|--|--|--|--|
| Size Code | EIA Code | Ler | ngth | Wi | dth | T4(min) | C(min) | | | | |
| | | L | Tol(±) | W | Tol(±) | T1(min.) | G(min.) | | | | |
| 1005 | 0402 | 1.00 | 0.05 | 0.50 | 0.05 | 0.05 | 0.30 | | | | |
| 1608 | 0603 | 1.60 | 0.15 | 0.80 | 0.10 | 0.10 | 0.50 | | | | |
| 2012 | 0805 | 2.00 | 0.20 | 1.25 | 0.15 | 0.10 | 0.65 | | | | |
| 3216 | 1206 | 3.20 | 0.30 | 1.60 | 0.20 | 0.15 | 1.00 | | | | |
| 3225 | 1210 | 3.20 | 0.40 | 2.50 | 0.25 | 0.15 | 1.05 | | | | |
| 4520 | 1808 | 4.50 | 0.40 | 2.00 | 0.25 | 0.20 | 1.50 | | | | |
| 4532 | 1812 | 4.50 | 0.40 | 3.20 | 0.30 | 0.20 | 1.50 | | | | |
| 5750 | 2220 | 5.70 | 0.50 | 5.00 | 0.40 | 0.30 | 1.85 | | | | |

*3216 Size \geq 2.2 μ F 100V \Rightarrow L, W : Tol±0.30

(2) Construction of Termination



(Unit : mm)

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Specifications and Test Methods (For Automotive Applications)

| No. | AEC- | Q200 | Spec | cification | Test Methods and Conditions | | | | | |
|-----|----------------------------------|-----------------------|---|--|---|--|--|--|--|--|
| NO. | Test | ltem | Class I | Class II | | | | | | |
| 1 | Pre-and Post- Electrical Test | | | - | - | | | | | |
| | | Appearance | No defects which may affect | performance | | | | | | |
| 2 | High Temperature Exposure | Capacitance Change | Within $\pm 2.5\%$ or ± 0.25 pF (Whichever is larger) 30 pF min.: Q ≥ 1000 | Within ±10.0% (*Within ±12.5%) Rated Voltage 16V min.: 0.05 max. | Temperature : Max. operating temperature±3 ℃ Maintenance Time : 1000+48/-0 hrs | | | | | |
| | (Storage) | Q/D.F. | 30pF max.: Q≧400+20×C C: Nominal Capacitance (pF) | 10V: 0.075 max. *0.2 max. | Let sit for 24±2 hours at room temperature, then measure. | | | | | |
| | | I.R. | More than 10,000M Ω or 500 Ω (Whichever is smaller) | ₽F (*50Ω·F) | | | | | | |
| | | Appearance | No defects which may affect | performance | Perform the 1000 cycles according to the four heat treatments | | | | | |
| | | Capacitance Change | Within ±2.5% or ±0.25pF (Whichever is larger) | Within ±10.0% | listed in the following table. Let sit for 24±2 hours at room temperature, then measure. | | | | | |
| 3 | Temperature | | 30pF min.:Q≧1000 | Rated Voltage 16V min.: 0.05 max. | Step 1 2 3 4 Tume (%) 55.0(.0) 65.0 405.0(.0) 65.0 | | | | | |
| Ũ | Cycle | Q/D.F. | 30pF max.:Q≧400+20xC C: Nominal Capacitance (pF) | 10V: 0.075 max. *0.2 max. | Temp.(°C) -55+0/-3 25±2 125+3/-0 25±2 Time(min) 15±3 1 15±3 1 | | | | | |
| | | I.R. | More than 10,000MΩ or 500Ω (Whichever is smaller) | ₽F (*50Ω·F) | Initial measurement Perform the initial measurement according to Note 1 for Class | | | | | |
| 4 | Destructive Physical Anal | ysis | No defects or abnormalities | | Per EIA-469 | | | | | |
| | | Appearance | No defects which may affect | performance | Temperature : 25~65°C, Humidity : 80~98% | | | | | |
| | 5 Moisture | Capacitance Change | Within ±3.0% or±0.30pF (Whichever is larger) | Within ±12.5% | Cycle Time : 24 hrs/cycle, 10 cycles Let sit for 24±2 hours at room temperature, then measure. | | | | | |
| 5 | | Q/D.F. | 30pF min.: $Q \ge 350$ 10pF min. and 30pF max.: $Q \ge 275+5/2xC$ 10pF max.: $Q \ge 200+10xC$ C: Nominal Capacitance (pF) | Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max. | 70 ← 90-98%/RH → ← KH → 60 55 50 50 50 50 50 50 5 | | | | | |
| | I.R. | | More than 10,000MΩ or 500Ω (Whichever is smaller) | ₽F (*50Ω·F) | 15 10 5 0 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 Time (hrs) | | | | | |
| | | Appearance | No defects which may affect | performance | _ | | | | | |
| | | Capacitance Change | Within ±3.0% or ±0.30pF (Whichever is larger) | Within ±12.5% | Temperature : 85±3 °C Humidity : 80~85% | | | | | |
| 6 | Biased Humidity | Q/D.F. | 30pF min.: Q≧200 30pF max.: Q≧100+10/3×C C: Nominal Capacitance (pF) | Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max. | Applied Voltage : Rated Voltage and 1.3+0.2/-0V Maintenance Time : 1000+48/-0 hrs Let sit for 24±2 hours at room temperature, then measure. | | | | | |
| | | I.R. | More than 1,000M Ω or 50 Ω ·F (Whichever is smaller) | (*5Ω·F) | The charge/discharge current is less than 50mA. | | | | | |
| | | Appearance | No defects which may affect | performance | | | | | | |
| | | Capacitance Change | Within ±3.0% or ±0.30pF (Whichever is larger) | Within ±12.5% | - Temperature : Max. operating temperature±3℃ Applied Voltage : Rated Voltage × 200% (*150%) Maintenance Time : 1000+48/-0 hrs | | | | | |
| 7 | Operational Life | Q/D.F. | 30pF min.:Q \geq 350 10pF min. and 30pF max.: Q \geq 275+5/2xC 10pF max.: Q \geq 200+10xC C: Nominal Capacitance (pF) | Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max. | Let sit for 24±2 hours at room temperature, then measure. The charge/discharge current is less than 50mA. Initial Measurement for Class II Applied 200% of the rated voltage for one hour at 125±3°C. Remove and let sit for 24±2 hours at room temperature, then | | | | | |
| | | I.R. | More than 1,000M Ω or 50 Ω ·F (Whichever is smaller) | (*5Ω·F) | measure. | | | | | |

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| | Ī | | `````````````````````````````````````` | Automotive Applic | , |
|-----|------------------------------------|-----------------------|---|---|---|
| No. | | -Q200 | Speci | fication | Test Methods and Conditions |
| | Test | ltem | Class I | Class II | |
| 8 | External Visu | al | No defects or abnormalities | | Visual inspection |
| 9 | Physical Dime | ension | Within the specified dimensions | | Using calipers |
| | | Appearance | No defects which may affect ; | performance | |
| | | Capacitance Change | Within the specified tolerance | | |
| 10 | Resistance to Solvents | Q/D.F. | 30pF min.: Q≧1000 30pF max.: Q≧400+20xC C: Nominal Capacitance (pF) | Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. *0.125 max. | Per MIL-STD-202 Method 215 |
| | | I.R. | More than 10,000M Ω or 500 Ω f (Whichever is smaller) | | |
| | | Appearance | No defects which may affect p | performance | |
| | | Capacitance Change | Within the specified tolerance | | Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks) |
| 11 | Mechanical Shock | Q/D.F. | 30pF min.:Q≧1000 30pF max.:Q≧400+20xC C: Nominal Capacitance (pF) | Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. *0.125 max. | Test Pulse Wave form : Half-sine Duration : 0.5ms Peak value : 1,500G |
| | | I.R. | More than 10,000M Ω or 500 Ω -f (Whichever is smaller) | | Velocity change : 4.7m/s |
| | | Appearance | No defects or abnormalities | | |
| | | Capacitance Change | Within the specified tolerance | | The specimens should be subjected to a simple harmonic motion |
| 12 | 2 Vibration Q/D.F. | | 30pF min.:Q≧1000 30pF max.:Q≧400+20xC C: Nominal Capacitance (pF) | Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. | having a total amplitude of 1.5mm. The entire frequency range of 10 to 2,000 Hz and return to 10 Hz should be traversed in 20 minutes. This cycle should be performed 12 times in each of three mutually perpendicular directions (total of 36 times). |
| | | I.R. | More than 10,000MΩ or 500Ω-f (Whichever is smaller) | *0.125 max. = (*50Ω·F) | - |
| | | Appearance | No defects which may affect p | performance | |
| | | Capacitance Change | Within the specified tolerance | 1 | Temperature (Eutectic solder solution) : 260 ± 5 °C |
| 13 | Resistance to Soldering Heat | Q/D.F. | 30pF min.:Q≧1000 30pF max.:Q≧400+20×C C: Nominal Capacitance (pF) | Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. | Dipping Time : 10±1s Let sit for 24±2 hours at room temperature, then measure. Initial measurement |
| | | I.R. | More than 10,000MΩ or 500Ωł (Whichever is smaller) | *0.125 max. = (*50Ω·F) | Perform the initial measurement according to Note 1 for Class II. |
| | | Appearance | No defects which may affect p | performance | Perform the 300 cycles according to the two heat treatments listed |
| | | Capacitance Change | Within ±2.5% or ±0.25pF (Whichever is larger) | Within ±15.0% | in the following table. Transfer Time : 20sec. max. |
| 14 | Thermal Shock | Q/D.F. | 30pF min.:Q≧1000 30pF max.:Q≧400+20xC C: Nominal Capacitance (pF) | Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. | Let sit for 24 ± 2 hours at room temperature, then measure.Step1Temp.(°C)-55+0/-3125+3/-0Time(min)15+3 |
| | | I.R. | More than 10,000MΩ or 500Ωf (Whichever is smaller) | *0.125 max. | Time(min.) 15±3 15±3 Initial measurement Perform the initial measurement according to Note 1 for Class II. |

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Specifications and Test Methods (For Automotive Application)

| | AEC-0 | Q200 | Specif | fication | | Test Matheda and Oser litization | | | | |
|--|----------------------|---|---|--|--|--|--|--|--|--|
| No. | Test | | Class | Class | П | Test Methods and Conditions | | | | |
| | | Appearance Capacitance | No defects which may affect pe Within the specified tolerance | erformance | | - | | | | |
| 15 | ESD | Change Q/D.F. | 30pF min.:Q≧1000 30pF max.:Q≧400+20xC C: Nominal Capacitance (pF) | 16V: | 0.025 max. 0.03 max. 0.035 max. 0.05 max. | Per AEC-Q200-002 | | | | |
| | | I.R. | More than 10,000M Ω or 500 Ω ·F | (*50Ω·F) | | | | | | |
| 16 | Solderability | | (Whichever is smaller) 95% of the terminations is to be s | oldered evenly and c | ontinuously. | (a) Preheat at 155 °C for 4 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5 °C. (b) Steam aging for 8 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5 °C. (c) Steam aging for 8 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution of ethanol and rosin. Immerse in eutectic solder solution of ethanol and rosin. Immerse in eutectic solder solution of ethanol and rosin. Immerse in eutectic solder solution of ethanol and rosin. Immerse in eutectic solder solution for 120±5 seconds at 260±5 °C. | | | | |
| | | Appearance | No defects or abnormalities | | | The capacitance/Q/D.F. should be measured at 25 °C at the | | | | |
| | | Capacitance Change | Within the specified tolerance | | | Class Capacitance CC Frequency Voltage Class Capacitance (C) Frequency Voltage Class Capacitance (C) Frequency Voltage Class Capacitance (C) Frequency Voltage | | | | |
| Electrical 17 Characteriza- tion | Q/D.F. | 30pF min.:Q≧1000 30pF max.:Q≧400+20xC C: Nominal Capacitance (pF) | 16V: | 0.025 max. 0.03 max. 0.035 max. 0.05 max. | $\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$ | | | | | |
| | | I.R. at 25℃ | More than 100,000M Ω or 1,000 $\Omega\cdot F$ (Whichever is smaller) | More than 10,000M (*50Ω·F) (Whicheve | | Should be measured with a DC voltage not exceeding rated | | | | |
| | | I.R. at 125℃ | More than 10,000M Ω or 100 Ω ·F (Whichever is smaller) | More than 1,000MΩ (*1Ω·F) (Whichever | | voltage at 25 $^\circ\!\!\!\mathrm{C}$ and 125 $^\circ\!\!\!\mathrm{C}$ for 2 minutes of charging. | | | | |
| | | Dielectric Strength | No dielectric breakdown or mecha | anical breakdown | | Applied 250% of the rated voltage for 1~5 seconds The charge/discharge current is less than 50mA. | | | | |
| | | | No defects which may affect pe | erformance | | Apply a force in the direction shown in the following figure for 60±5 seconds. | | | | |
| 18 | Board Flex | Capacitance Change | Within ±5.0% or ±0.5pF (Whichever is larger) | Within the specified | tolerance | 45±2 45±2 Probe to exert bending force Speed: 1.0mm/s Printed circuit board under test Flexure for Class I: 3mm max. | | | | |
| | Tamain I | Appearance | No defects which may affect pe | l erformance | | for Class II: 2mm max. Apply 18N ¹⁾ force in parallel with the test jig for 60±1 seconds. | | | | |
| 19 | Terminal Strength | Capacitance | Within ±5.0% or ±0.5pF | Within the specified | toloropoo | ¹⁾ 10N for 1608(EIA:0603) size | | | | |

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| | ecificatio | | AEC-Q200 Specification | | | | | | | | | | Τ |
|-----|----------------------------|--|----------------------------------|---------|--|----------|--|---|--------------------------|--------------------------|---------------------------|---------|---|
| No. | | Item | Class | | | Class | Test Methods and Conditions | | | | | | |
| | | | The chip endure following force. | | | | | Apply a force as shown in the following figure. | | | | | |
| | | | Chip Length | Thickne | ess (T) | Force | (i) Chip Lengtl Beam Spe | | ` | ii) Chip Le | ngth : 3.2 peed : 2.5 | | |
| | | | 2.5mm max. | T≤0.5 | ōmm | 8N | Beam Spe | eu . 0.5m | 11/5 | Deam 3 | peed . z.: | 51111/5 | |
| 20 | Beam Load T | est | 2.511111 11187. | T>0.5 | ōmm | 20N | | | | | | | |
| | | | 3.2mm min. | T<1.2 | 5mm | 15N | 0 | lro | on Board | | | | |
| | | | 3.2000 000 | T≥1 | .25 | 54.5N | | | | | 0.6 | | |
| | | | - | | _ | | | | | | * * | | |
| | | Capacitance Change | | | X7R : Wit X7S : Wit X6S : Wit X7T : Wit | nin ±22% | (i) Class I The temperate measured in s sequentially fr | a reference through 5 | e. When cy , the capa | cling the citance sh | temperatu nould be | | |
| 21 | Capacitance Temperature | Temperature Coefficient | 0±30 ppm/℃ | | | | within the spe The capacitan between the n 1, 3 and 5 by | ice drift is naximum | calculated and minim | l by dividin um measu | g the diffe ired value | erences | |
| 21 | Characteris- | | | | | | Step | 1 | 2 | 3 | 4 | 5 | |
| | tics | | | | | | Temp.(℃) | 25±2 | -55±3 | 25±2 | 125±3 | 25±2 | |
| | | Capacitance Within ±0.2% or ±0.05pF Drift (Whichever is larger) | | | | | (ii) Class II The ranges of over the temp Initial measure Perform the in | erature ra ement | inge from - | 55℃ to 12 | 5℃. | | |

In the case of "*" is specifications for "Thin Layer Large Capacitance Type"

Note 1. Initial Measurement for Class II

Perform a heat treatment at 150+0/-10 °C for one hour, and then let sit for 24±2 hours at room temperature, then measure.

| SW - Q - 01A | |
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Packing

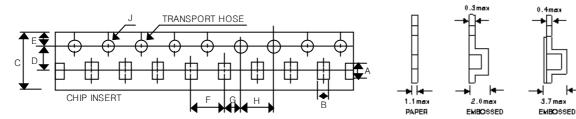
- (1) Bulk Packing
 - 1 1000 pcs per polybag
 - 2 5 polybags per inner box
 - 3 10 inner boxes per out box
- (2) Reel Packing
 - (1) 8~10 reels per inner box
 - 2 6 inner boxes per out box
- (3) Reel Dimensions

| E | Π | | | | | | | | (Ui | nit : mm) |
|-----------------------|------------|-----------|-----------|-----------|----------------|----------------|---------|-----------------|-------|-----------|
| | L I_ | Mark | Size Code | EIA Code | Α | В | С | D | Е | w |
| \Q1/î | ſ <u>I</u> | 7 " Reel | 1005~3225 | 0402~1210 | Ф 178±2 | Ф 50Min | Ф13±0.5 | Ф 21±0.8 | 2±0.5 | 10±1.5 |
| \setminus \square | | | 4520~4532 | 1808~1812 | Ф180+0,-3 | Ф60-0,+1 | Φ13±0.2 | Φ57-0+1 | 3±0.2 | 13±0.5 |
| $\sim \rightarrow$ | U w U | 13 " Reel | 1005~3225 | 0402~1210 | Ф 330±2 | Ф70Min | Ф13±0.5 | Ф21±0.8 | 2±0.5 | 10±1.5 |

(4) Number of Package

| Size Code | EIA Code | 7" | 13" | | |
|-----------|----------|--------------------|--------------------|--|--|
| | | Quantity(pcs)/Reel | Quantity(pcs)/Reel | | |
| 1005 | 0402 | 10,000 | 50,000 | | |
| 1608 | 0603 | 4,000 | 15,000 | | |
| 2012 | 0805 | 3,000 ~ 4,000 | 8,000 ~ 15,000 | | |
| 3216 | 1206 | 2,000 ~ 4,000 | 6,000 ~ 10,000 | | |
| 3225 | 1210 | 1,000 ~ 3,000 | 4,000 ~ 10,000 | | |
| 4520 | 1808 | 1,500 ~ 3,000 | _ | | |
| 4532 | 1812 | 500 ~ 1,000 | 1,500 ~ 5,000 | | |

(5) Tape Dimensions



| Size Code | EIA Code | А | В | С | D | E | F | G | н | J |
|-----------|----------|----------|----------|----------|----------|----------|--------------------|---------|---------|---------|
| 1005 | 0402 | 1.15±0.1 | 0.65±0.1 | 8.0±0.3 | 3.5±0.05 | 1.75±0.1 | 2.0±0.05 | 2.0±0.1 | 4.0±0.1 | 1.5±0.1 |
| 1608 | 0603 | 1.9±0.2 | 1.10±0.2 | 8.0±0.3 | 3.5±0.05 | 1.75±0.1 | 4.0±0.1 | 2.0±0.1 | 4.0±0.1 | 1.5±0.1 |
| 2012 | 0805 | 2.4±0.2 | 1.65±0.2 | 8.0±0.3 | 3.5±0.05 | 1.75±0.1 | 4.0±0.1 | 2.0±0.1 | 4.0±0.1 | 1.5±0.1 |
| 3216 | 1206 | 3.6±0.2 | 2.00±0.2 | 8.0±0.3 | 3.5±0.05 | 1.75±0.1 | 4.0±0.1 | 2.0±0.1 | 4.0±0.1 | 1.5±0.1 |
| 3225 | 1210 | 3.6±0.2 | 2.80±0.2 | 8.0±0.3 | 3.5±0.05 | 1.75±0.1 | 4.0±0.1 | 2.0±0.1 | 4.0±0.1 | 1.5±0.1 |
| 4520 | 1808 | 4.8±0.2 | 2.3±0.2 | 12.0±0.3 | 5.5±0.1 | 1.75±0.1 | 4.0±0.1 8.0±0.1 | 2.0±0.1 | 4.0±0.1 | 1.5±0.1 |
| 4532 | 1812 | 4.9±0.2 | 3.6±0.2 | 12.0±0.3 | 5.5±0.1 | 1.75±0.1 | 8.0±0.1 | 2.0±0.1 | 4.0±0.1 | 1.5±0.1 |

| BLAN K | CHIPS | BLA | NK | LEADER |
|----------------------|----------------|------------|--|--------------|
| 10 to 20pitch | • | 20 to 4 | 0pitch | 200 to 250mm |
| ••••••••••••• | ••• | + ⊕⊕⊕⊕⊕ | ϕ | ¢ |
| | | | -0 0 0 |] |
| DRA | WING DIRECTION | | | |

| | | SW - Q - 01A 8 / 9 | | | |
|---|--|---|--|--|--|
| aution | | | | | |
| Storage Condition When solderability is considered (1) Temperature: 25°C ± 10°C (2) Relative Humidity: Below 7 | | ded to be used in 12 months. | | | |
| The Regulation of Environment Never use materials mentioned Pb, Cd, Hg, Cr⁺⁶, PBB(Polybrock) | d below in MLCC products | regulated this document. olybrominated diphenyl ethers), asbestos | | | |
| Mounting Position Choose a mounting position the imposed on the chip during flee board. | | [Component direction] ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ | | | |
| | | [Chip Mounting Close to Board Separation Point] | | | |
| The sudden temperature changes damages to ceramic componer procedures should be required components. Please refer to the recommend shown in figures, and keep the within the range recommended Table 1 | hts. Therefore, the preheating for the soldering of ceramic ed soldering profiles as temperature difference(\triangle T) | Recommended Reflow Soldering Profile for Lead Free Solder Infrared Reflow Temperature 250±10°C 200°C 160±10°C 140±10°C Preheating | | | |
| Size code (EIA Code) | Temperature Difference | | | | |
| 1005~3216 (0402~1206) | ∆T≤190 ℃ | 60~120 sec. 30~60 sec. | | | |
| 3225 (1210) | ∆T≤130 ℃ | Vapor Reflow Temperature | | | |
| | | 250±10°C 160±10°C 140±10°C Preheating 60~120 sec. 20 sec. max. | | | |

| | SW - Q - 01A | 9/9 |
|--|--------------|-----|
| Note | | |
| 'Aging'/'De-aging' behavior of high dielectric constant type MLCCs | | |

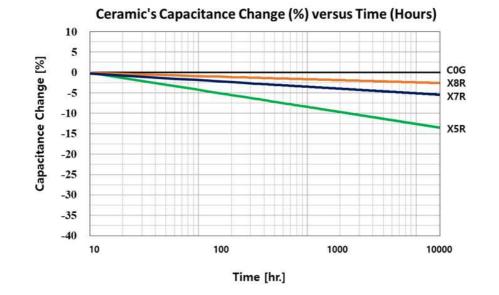
(Typically represented by X7R temperature characteristic of which main composition is BaTiO₃)

'Aging' / 'De-aging' Behavior of high dielectric MLCCs Please note that high dielectric type dielectric ceramic capacitors have a "normal" 'aging' behavior / characteristic, that is; their capacitance value decreases with time from its value when it was first manufactured. From that date, the capacitance value begins to decrease at a logarithmic rate defined by:

$C_t = C_{24} (1 - k \log 10 t)$

where,

- $C_t\;$: Capacitance value, t hours after the start of 'aging'
- $C_{\rm 24}$: Capacitance value, 24 hours after its manufacture
- k : Aging constant (capacitance decrease per decade-hour)
- t : time, in hours, from the start of 'aging'



The capacitance value can be restored (also known as 'de-aged') by exposing the component to elevated temperatures approaching its curie temperature (approximately 120°C). This 'de-aging' can occur during the component's solder-assembly onto the PCB, during life or temperature cycle testing, or by baking at 150°C for about 1 hour.